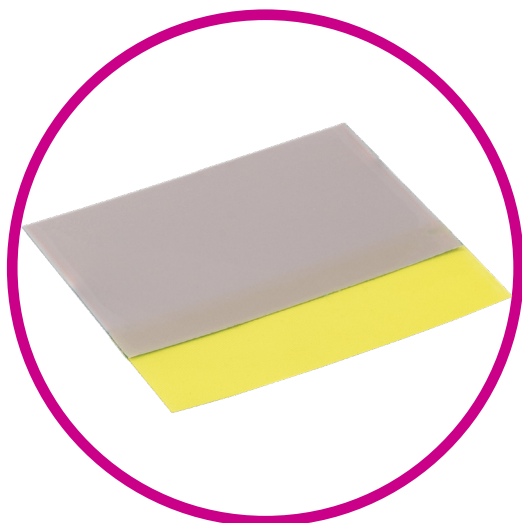


THERMAL PADS | HSP-8

ACCESSORIES



Features

- Thermal Pad suitable for NOVA22 PM67 Panel Mount SSRs
- Easy to use thermal interface material
- Excellent alternative to thermal grease



GENERAL SPECIFICATIONS

Description	Parameters
Material	Chomerics T725
Color	Pink
Thickness [inch (mm)]	0.005 (0.127)
Adhesive	No
Thermal Impedance [°C-in ² /W] (1)	0.06 @ 25 psi
Thermal Conductivity [W/m-K] (1)	0.07
Flame Rating	V0
Continuous Temperature Range [°C]	-55 to 125
Volume Resistivity [Ohm-cm]	> 10 ¹⁴



MOUNTING SURFACE PREPARATION

The mounting surface, usually the heat sink, should be clean and free from machining oils and aluminum dust, and may be cleaned with any common solvent, such as isopropyl alcohol (IPA) if necessary. The surface of the heat sink may be anodized, chromate coated or unfinished aluminum.



INSTALLATION OF HSP-8 PADS

HSP-8 material does not require pre-heating of the heat sink prior to installing the HSP-8 pad onto the heat sink, because of the phase change nature of the HSP-8 material, please follow the process temperature/pressure guidelines below to ensure the best results for a specific assembly process:

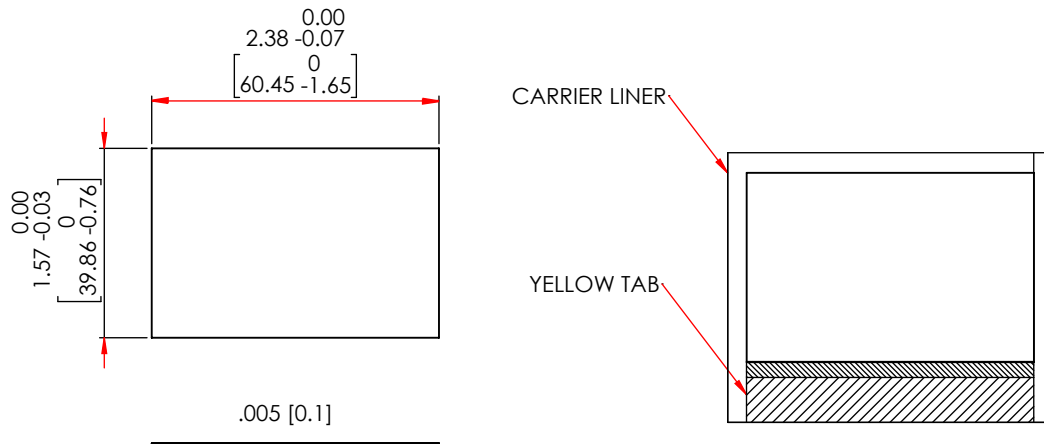
Temperature / Pressure	
Process Step	Recommended Range
Removing pad from clear carrier liner	Temp. of Roll: less than 38°C (100°F)
Installing pad onto "cold" heat sink	Heat Sink Temp: 16°C to 38°C (60°F to 100°F)
	Roll Temp: 21°C to 38°C (70°F to 100°F)
	Installation Pressure: 25 to 50 psi (2)
Installing pad onto "warm" heat sink	Heat Sink Temp: 24°C to 38°C (75°F to 100°F)
	Roll Temp: 21°C to 38°C (70°F to 100°F)
	Installation Pressure: 25 to 50 psi (2)
Removing protective blue release liner	Temp of Heat Sink/Pad Assembly: Less than 38°C (100°F)

When removing the pull-tab, use a quick, lifting motion. This is preferable over peeling the pull-tab from the HSP-8 pad and heat sink. To ensure optimal "wetting" of the HSP-8 pad to the heat sink. It is recommended that the parts be allowed to dwell one hour prior to attempting release liner removal.



MECHANICAL SPECIFICATIONS

Tolerances: ± 0.02 in / 0.5 mm
All dimensions are in: inches [Millimeters]



GENERAL NOTES

- (1) This value is provided for reference only. Follow installation instructions for accurate thermal performance.
- (2) Apply pressure to the HSP-8 pad with a soft "press-pad" for 2 to 3 seconds.



WARNINGS



RISK OF MATERIAL DAMAGE AND HOT ENCLOSURE

- The product's side panels may be hot, allow the product to cool before touching.
- Follow proper mounting instructions including torque values.
- Do not allow liquids or foreign objects to enter this product.

Failure to follow these instructions can result in serious injury, or equipment damage.



HAZARD OF ELECTRIC SHOCK, EXPLOSION OR ARC FLASH

- Disconnect all power before installing or working with this equipment.
- Verify all connections and replace all covers before turning on power.

Failure to follow these instructions will result in death or serious injury.

Sensata Technologies, Inc. ("Sensata") data sheets are solely intended to assist designers ("Buyers") who are developing systems that incorporate Sensata products (also referred to herein as "components"). Buyer understands and agrees that Buyer remains responsible for using its independent analysis, evaluation and judgment in designing Buyer's systems and products. Sensata data sheets have been created using standard laboratory conditions and engineering practices. Sensata has not conducted any testing other than that specifically described in the published documentation for a particular data sheet. Sensata may make corrections, enhancements, improvements and other changes to its data sheets or components without notice.

Buyers are authorized to use Sensata data sheets with the Sensata component(s) identified in each particular data sheet. HOWEVER, NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER SENSATA INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY THIRD PARTY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT, IS GRANTED HEREIN. SENSATA DATA SHEETS ARE PROVIDED "AS IS". SENSATA MAKES NO WARRANTIES OR REPRESENTATIONS WITH REGARD TO THE DATA SHEETS OR USE OF THE DATA SHEETS, EXPRESS, IMPLIED OR STATUTORY, INCLUDING ACCURACY OR COMPLETENESS. SENSATA DISCLAIMS ANY WARRANTY OF TITLE AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, QUIET ENJOYMENT, QUIET POSSESSION, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS WITH REGARD TO SENSATA DATA SHEETS OR USE THEREOF.

All products are sold subject to Sensata's terms and conditions of sale supplied at www.sensata.com SENSATA ASSUMES NO LIABILITY FOR APPLICATIONS ASSISTANCE OR THE DESIGN OF BUYERS' PRODUCTS. BUYER ACKNOWLEDGES AND AGREES THAT IT IS SOLELY RESPONSIBLE FOR COMPLIANCE WITH ALL LEGAL, REGULATORY AND SAFETY-RELATED REQUIREMENTS CONCERNING ITS PRODUCTS, AND ANY USE OF SENSATA COMPONENTS IN ITS APPLICATIONS, NOTWITHSTANDING ANY APPLICATIONS-RELATED INFORMATION OR SUPPORT THAT MAY BE PROVIDED BY SENSATA.

Mailing Address: Sensata Technologies, Inc., 529 Pleasant Street, Attleboro, MA 02703, USA.

CONTACT US

Americas

+1 (877) 502 5500 – Option 2
sales.crydom@sensata.com

Europe, Middle East & Africa

+44 (1202) 416170
ssr-info.eu@sensata.com

Asia Pacific

sales.isasia@list.sensata.com
China +86 (21) 2306 1500
Japan +81 (45) 277 7117
Korea +82 (31) 601 2004
India +91 (80) 67920890
Rest of Asia +886 (2) 27602006
ext 2808

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Sensata:](#)

[HSP-8](#)